

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant:	Mark Rapaich et al.	Examiner:	Tung Minh Bui
Serial No.:	Unknown	Group Art Unit:	2835
Filed:	October 4, 1999	Docket:	450.309US2
Title:	MODULAR COMPUTER		
(Continuation of Application Serial No. 09/410,938, filed October 9, 1999)			

PRELIMINARY AMENDMENT

Commissioner for Patents
Washington, D.C. 20231

Prior to examination, please amend the above-identified continuation application as follows.

IN THE SPECIFICATION

On page 1, after the title, please insert the following "Related Application" section:

--Related Application

This application is a non-provisional application claiming benefit under 35 U.S.C. § 120 of co-pending non-provisional U.S. Application No. 09/410,938, filed October 4, 1999.--

IN THE CLAIMS

Please cancel claims 1-11 and 13-18 without prejudice or disclaimer.

Please add the following new claims 19-38.

1 - 11. (Canceled)

12. (Previously Canceled)

13-18. (Canceled)

19. (New) A method of manufacturing an information handling system, comprising:

manufacturing a lower chassis having a housing, a motherboard, memory, a plurality of expansion drive bays, and a connector for connection to an external supply of DC power, wherein the motherboard, the memory, and the plurality of expansion drive bays are connected to the housing of the lower chassis;

PRELIMINARY AMENDMENT

Serial Number: Not Assigned
Filing Date: Herewith
Title: MODULAR COMPUTER

Page 2
Dkt: 450.309US2

manufacturing an upper chassis having a housing, a display, and a power supply, wherein the upper chassis is manufactured at a different location than the lower chassis, and wherein the display and the power supply are connected to the housing of the upper chassis, wherein the upper chassis is manufactured to be disposed on top of the lower chassis, and wherein the lower chassis is manufactured to be disposed beneath the upper chassis; and

shipping the lower and the upper chassis directly to a customer without pre-assembly of the upper and lower chassis, wherein the shipping of either the upper or the lower chassis avoids import and export tariffs associated with shipping the entire information handling system.

20. (New) The method of claim 19, wherein the lower chassis further has a lower chassis blind mate connector.

21. (New) The method of claim 20, wherein the upper chassis further has an upper chassis blind mate connector.

22. (New) The method of claim 21, wherein the lower and upper chassis are connectable by the upper and lower chassis blind mate connectors to pass signals therebetween.

23. (New) The method of claim 22, wherein the lower and upper chassis are only operational when connected via the upper and lower chassis blind mate connectors.

24. (New) The method of claim 19, wherein the lower chassis has a plurality of guide pins extending therefrom, and wherein the upper chassis has a plurality of mating guide pin openings for connecting the upper and lower chassis.

25. (New) The method of claim 21, wherein the upper chassis further comprises an AC to DC power converter, and the upper chassis blind mate connector is for passing only DC power to the lower chassis.

0986431-063101
TOTAL 10

PRELIMINARY AMENDMENT

Serial Number: Not Assigned
Filing Date: Herewith
Title: MODULAR COMPUTER

Page 3
Dkt: 450.309US2

26. (New) The method of claim 19, wherein manufacturing the lower chassis further comprises: manufacturing the lower chassis to fit substantially flush with the upper chassis.

27. (New) The method of claim 19, wherein manufacturing the upper chassis further comprises: manufacturing the upper chassis to fit substantially flush with the lower chassis.

28. (New) The method of claim 19, wherein the import and export tariffs are avoided by neither the upper chassis nor the lower chassis alone being classified as a computer.

29. (New) The method of claim 19, wherein the upper chassis and lower chassis are connectable without cabling.

30. (New) A method of manufacturing an information handling system, comprising:

- manufacturing a lower chassis having a housing, a motherboard, memory, a plurality of expansion drive bays, and a connector for connection to an external supply of DC power, wherein the motherboard, the memory, and the plurality of expansion drive bays are connected to the housing of the lower chassis;
- manufacturing an upper chassis having a housing, a display, and a power supply, wherein the upper chassis is manufactured at a different location than the lower chassis, and wherein the display and the power supply are connected to the housing of the upper chassis, wherein the upper chassis is manufactured to be disposed on top of the lower chassis, and wherein the lower chassis is manufactured to be disposed beneath the upper chassis; and
- shipping the lower and the upper chassis directly to a customer without pre-assembly of the upper and lower chassis, wherein shipping the lower and upper chassis directly from the manufacturing location reduces shipping costs when the lower and upper chassis are manufactured at different locations.

31. (New) The method of claim 30, wherein the lower chassis further has a lower chassis blind mate connector.

0986481-063401

PRELIMINARY AMENDMENT

Serial Number: Not Assigned
Filing Date: Herewith
Title: MODULAR COMPUTER

Page 4
Dkt: 450.309US2

32. (New) The method of claim 31, wherein the upper chassis further has an upper chassis blind mate connector.

33. (New) The method of claim 32, wherein the lower and upper chassis are connectable by the upper and lower chassis blind mate connectors to pass signals therebetween.

34. (New) The method of claim 33, wherein the lower and upper chassis are only operational when connected via the upper and lower chassis blind mate connectors.

35. (New) The method of claim 30, wherein the lower chassis has a plurality of guide pins extending therefrom, and wherein the upper chassis has a plurality of mating guide pin openings for connecting the upper and lower chassis.

36. (New) The method of claim 32, wherein the upper chassis further comprises an AC to DC power converter, and the upper chassis blind mate connector is for passing only DC power to the lower chassis.

37. (New) The method of claim 30, wherein manufacturing the lower chassis further comprises: manufacturing the lower chassis to fit substantially flush with the upper chassis.

38. (New) The method of claim 30, wherein manufacturing the upper chassis further comprises: manufacturing the upper chassis to fit substantially flush with the lower chassis.

REMARKS

Applicant has reviewed and considered the Office Action mailed on February 21, 2001 in parent application SN 09/410,938. Claims 1-11 and 13-18 are canceled without prejudice or disclaimer, and new claims 19-38 are added. Claim 12 was previously canceled. As a result, claims 19-38 are currently pending in this application. No new matter has been added by these amendments.

PRELIMINARY AMENDMENT

Serial Number: Not Assigned
Filing Date: Herewith
Title: MODULAR COMPUTER

Page 5
Dkt: 450.309US2

Applicant respectfully requests examination of the above-identified patent application as amended and in view of the following remarks.

Claim Objections

Claims 4-5 were objected to because of informalities. Applicant has canceled claims 4 and 5 without prejudice or disclaimer, so the objection is moot.

Claim Rejections under 35 U.S.C. § 112

Claims 15-16 were rejected under 35 U.S.C. 112, second paragraph as being indefinite "for failing to point out how to ship the chassis." The elements of claims 15 and 16 are incorporated into new claims 19 and 30, respectively. Insofar as these rejections are applied to claims 19 and 30, applicant respectfully submits that claims 19 and 30 fully comply with 35 U.S.C. 112, second paragraph, for the reasons argued below.

In rejecting a claim under the second paragraph of 35 U.S.C. § 112, it is incumbent on the examiner to establish that one of ordinary skill in the pertinent art, when reading the claims in light of the supporting specification, would not have been able to ascertain with a reasonable degree of precision and particularity the particular area set out and circumscribed by the claims. *Ex parte Wu*, 10 USPQ 2d 2031, 2033 (B.P.A.I. 1989)(citing *In re Moore*, 439 F.2d 1232, 169 USPQ 236 (C.C.P.A. 1971); *In re Hammack*, 427 F.2d 1378, 166 USPQ 204 (C.C.P.A. 1970)).

The M.P.E.P. adopts this line of reasoning, stating that:

The essential inquiry pertaining to this requirement is whether the claims set out and circumscribe a particular subject matter with a reasonable degree of clarity and particularity. Definiteness of claim language must be analyzed, not in a vacuum, but in light of:

- (1) The content of the particular application disclosure;
- (2) The teachings of the prior art; and
- (3) The claim interpretation that would be given by one possessing the ordinary level of skill in the pertinent art at the time the invention was made. *M.P.E.P.* § 2173.02.

PRELIMINARY AMENDMENT

Serial Number: Not Assigned
Filing Date: Herewith
Title: MODULAR COMPUTER

Page 6
Dkt: 450.309US2

Applicant respectfully submits that the claim language in question, when analyzed in light of the content of the application disclosure and prior art, is not indefinite. Applicant is using the word "shipping" according to the ordinary dictionary definition. For the Examiner's convenience, enclosed is a copy of the "ship" dictionary definition: "to cause to be transported." Thus, it is not necessary to specify a specific means of transportation in applicant's claim because any appropriate means of shipping may be used.

Further, claim 19 recites "shipping of either the upper or the lower chassis avoids import and export tariffs associated with shipping the entire information handling system." Thus, it is clear that the tariffs that would be incurred by shipping the entire system are avoided by shipping either chassis alone. This claim language is supported, for example, by applicant's specification at page 8, lines 18-21.

Further, claim 30 recites "shipping the lower and upper chassis directly from the manufacturing location reduces shipping costs when the lower and upper chassis are manufactured at different locations." Thus, it is clear that shipping the lower and upper chassis directly from their respective manufacturing locations avoids the cost of shipping one or both to a common location where they would be assembled together. This claim language is supported, for example, by applicant's specification at page 8, lines 12-17.

Conclusion

Applicant respectfully submits that the claims are in condition for allowance and notification to that effect is earnestly requested. The Examiner is invited to telephone Applicant's attorney (612-371-2103) to facilitate prosecution of this application.

PRELIMINARY AMENDMENT

Serial Number: Not Assigned
Filing Date: Herewith
Title: MODULAR COMPUTER

Page 7
Dkt. 450.309US2

If necessary please charge any additional fees or credit overpayment to Deposit Account
No. 50-0439.

Respectfully submitted,

MARK RAPAICH ET AL.

By their Representatives,

SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.
P.O. Box 2938
Minneapolis, MN 55402
(612) 371-2103

Date: 6/21/2001

By Owen J. Gamon
Owen J. Gamon
Reg. No. 36,143

"Express Mail" mailing label number: EL 721295344 US

Date of Deposit: June 21, 2001

This paper or fee is being deposited on the date indicated above with the United States Postal Service pursuant to 37 CFR 1.10, and is addressed to the Commissioner for Patents, Box Patent Application, Washington, D.C. 20231.

09886481 063101
"063101" 09886481